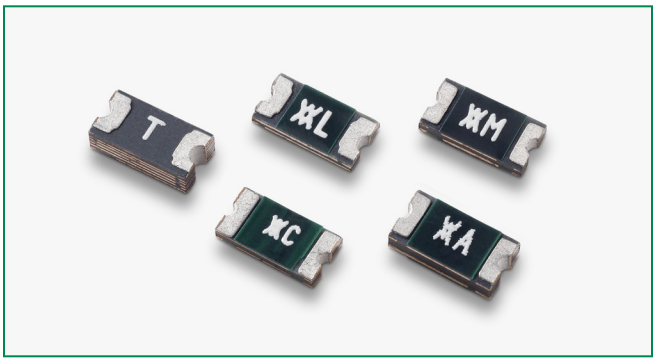
nanoSMDC Series



Agency Approvals

AGENCY	AGENCY FILE NUMBER
c UL us	E74889
CSA	78165
TÜV	72161782

Description

The nanoSMDC series provides surface mount overcurrent protection for applications where space is at a premium and resettable protection is desired.

Features

- Broadest range of resettable devices available in industry
- Low resistance
- Small 1206 footprint
- Fast time-to-trip
- RoHS complaint, lead-free and halogen-free

Applications

Mobile Electronics and Batteries

- Computer
- Portable electronics
- Multimedia
- Game machines
- Telephone and broadband
- Automotive
- Industrial controls
- Battery

Additional Information

Datasheet | Resources | Samples

Electrical Characteristics

Part Number	I_H (A)	I_T (A)	V_{MAX} (V_{DC})	I_{MAX} (A)	$P_{D\,MAX}$ (W)	Max Time-to-trip (A)	Max Time-to-trip (s)	R_{MIN} (Ω)	R_{1MAX} (Ω)
nanoSMDC Series — Size 3216mm/1206mils									
nanoSMDC010F	0.10	0.25	60	10	0.80	0.50	1.00	1.60	15.00
nanoSMDC012F	0.12	0.39	48	10	0.50	1.00	0.20	1.40	6.50
nanoSMDC016F	0.16	0.45	48	10	0.50	1.00	0.30	1.10	5.00
nanoSMDC020F	0.20	0.42	24	100	0.60	8.00	0.10	0.65	3.10
nanoSMDC025F	0.25	0.58	16	100	0.60	8.00	0.10	0.40	2.10
nanoSMDC035F	0.35	0.75	16	20	0.60	3.50	0.10	0.45	1.35
nanoSMDC050F/13.2	0.50	1.10	13.2	100	0.80	8.00	0.10	0.20	0.75
nanoSMDC075F	0.75	1.50	6	100	0.80	8.00	0.10	0.09	0.30
nanoSMDC110F	1.10	2.20	6	100	0.80	8.00	0.10	0.07	0.20
nanoSMDC150F	1.50	3.00	6	100	0.80	8.00	0.30	0.04	0.11
nanoSMDC200F	2.00	4.00	6	100	1.00	8.00	1.50	0.02	0.072

Notes:

I_H : Hold current: maximum current device will pass without interruption in 20°C still air.
I_T : Trip current: minimum current that will switch the device from low resistance to high resistance in 20°C still air.
V_{MAX} : Maximum continuous voltage device can withstand without damage at rated current.
I_{MAX} : Maximum fault current device can withstand without damage at rated voltage.
P_D : Power dissipated from device when in the tripped state in 20°C still air.
R_{MIN} : Minimum resistance of device as supplied at 20°C unless otherwise specified.
R_{1MAX} : Maximum resistance measured one hour post-trip or post-reflow at 20°C.

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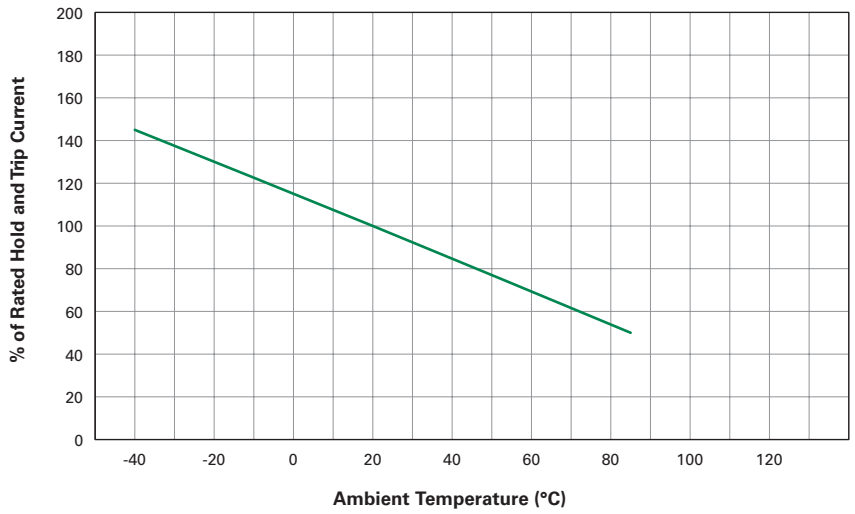
Temperature Rerating

Maximum Ambient Temperature											
Part Number	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	80°C	85°C
Hold Current (A)											
nanoSMDC Series — Size 3216mm/1206mils											
nanoSMDC010F	0.15	0.14	0.12	0.10	0.10	0.09	0.08	0.07	0.06	0.05	0.05
nanoSMDC012F	0.20	0.17	0.15	0.13	0.12	0.11	0.10	0.09	0.08	0.07	0.07
nanoSMDC016F	0.21	0.20	0.18	0.16	0.16	0.14	0.13	0.12	0.11	0.10	0.09
nanoSMDC020F	0.34	0.30	0.26	0.22	0.20	0.17	0.15	0.13	0.11	0.09	0.08
nanoSMDC025F	0.38	0.33	0.30	0.26	0.25	0.22	0.20	0.19	0.16	0.13	0.11
nanoSMDC035F	0.58	0.51	0.44	0.38	0.35	0.31	0.28	0.24	0.21	0.18	0.16
nanoSMDC050F/13.2	0.78	0.69	0.61	0.52	0.50	0.44	0.39	0.35	0.30	0.25	0.24
nanoSMDC075F	1.15	1.04	0.92	0.78	0.75	0.69	0.63	0.58	0.51	0.46	0.43
nanoSMDC110F	1.64	1.46	1.30	1.10	1.06	0.92	0.83	0.80	0.65	0.56	0.52
nanoSMDC150F	2.20	1.99	1.77	1.55	1.50	1.34	1.23	1.10	1.01	0.90	0.84
nanoSMDC200F	2.92	2.64	2.35	2.07	2.00	1.79	1.64	1.50	1.36	1.22	1.15

Temperature Rerating Curve



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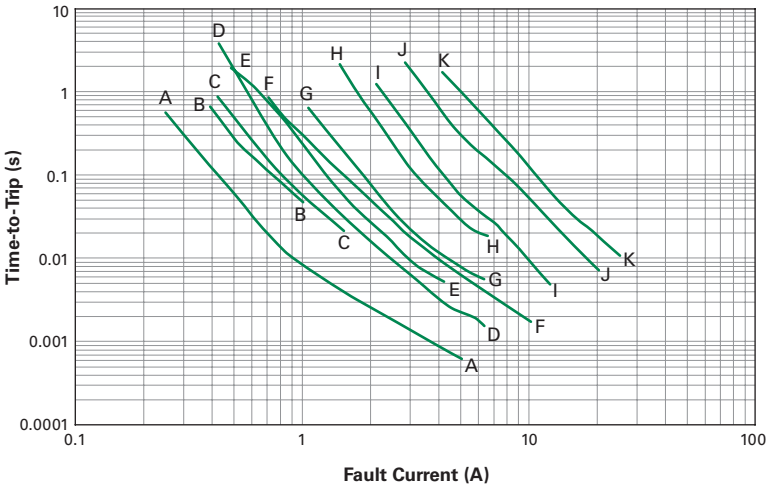
Typical Time-to-Trip Curves at 20°C

nanoSMDCxxxF

A = nanoSMDC010F
B = nanoSMDC012F
C = nanoSMDC016F
D = nanoSMDC020F
E = nanoSMDC025F
F = nanoSMDC035F
G = nanoSMDC050F/13.2
H = nanoSMDC075F
I = nanoSMDC110F
J = nanoSMDC150F
K = nanoSMDC200F



Physical Specifications

Terminal Pad Material	100% Matte Tin with Nickel Underplate
Soldering Characteristics	ANSI/J-STD-002 Category 3
Solder Heat Withstand	per IEC-STD 68-2-20, Test Tb, Section 5, Method 1a
Flammability Resistance	per IEC 695-2-2 Needle Flame Test for 20 seconds

Environmental Specifications

Test	Test Method	Conditions	Resistance Change
Storage Life	PS300, Section 5.3.2	60°C, 1000 hrs 85°C, 1000 hrs	±3% typ ±3% typ
Humidity Aging	PS300, Section 5.3.1	85°C, 85% R.H., 100 hrs	±1.2% typ
Thermal Shock	MIL-STD-202, Method 107G	85°C, -40°C (20 Times) 125°C, -55°C (10 Times)	-33% typ -33% typ
Vibration	MIL-STD-883C	per MIL-STD-883C	No Change
Solvent Resistance	PS300, Section 5.2.2	Freon Trichloroethane Hydrocarbons	No Change No Change No Change

Moisture Resistance Level	Level 2a, J-STD-020
Storage Conditions	40°C max, 70% RH max; devices should remain in original sealed bags prior to use. Devices may not meet specified values if these storage conditions are exceeded.

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Dimension Figures

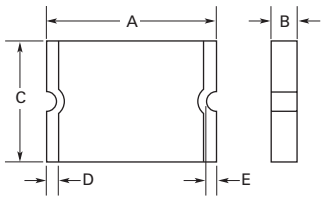

Figure 1

Dimensions

Part Number	Dimensions in Millimeters (Inches)										Figure
	A		B		C		D		E		
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
femtoSMDC Series — Size 1608mm/0603mils											
nanoSMDC010F	3.00 (0.118)	3.40 (0.134)	0.62 (0.024)	1.00 (0.039)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC012F	3.00 (0.118)	3.40 (0.134)	0.62 (0.024)	1.00 (0.039)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC016F	3.00 (0.118)	3.40 (0.134)	0.62 (0.024)	1.00 (0.039)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC020F	3.00 (0.118)	3.40 (0.134)	0.58 (0.023)	0.82 (0.032)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC025F	3.00 (0.118)	3.40 (0.134)	0.58 (0.023)	0.82 (0.032)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC035F	3.00 (0.118)	3.40 (0.134)	0.58 (0.023)	0.82 (0.032)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC050F/13.2	3.00 (0.118)	3.40 (0.134)	0.50 (0.019)	0.74 (0.029)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC075F	3.00 (0.118)	3.40 (0.134)	0.44 (0.017)	0.68 (0.027)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC110F	3.00 (0.118)	3.40 (0.134)	0.28 (0.011)	0.67 (0.026)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC150F	3.00 (0.118)	3.40 (0.134)	0.55 (0.022)	0.89 (0.035)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1
nanoSMDC200F	3.00 (0.118)	3.40 (0.134)	0.83 (0.033)	1.10 (0.043)	1.37 (0.054)	1.80 (0.071)	0.25 (0.010)	0.75 (0.030)	0.076 (0.003)	—	1

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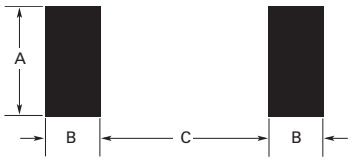
Recommended Pad Layout



Packaging and Marking Information

Part Number	Tape and Reel Quantity	Standard Package	Part Marking	Recommended Pad Layout Figures [mm (in)]			Agency Recognition
				Dimension A (Nom)	Dimension B (Nom)	Dimension C (Nom)	
nanoSMDC Series — Size 3216mm/1206mils							
nanoSMDC010F	3,000	15,000	A	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, TÜV
nanoSMDC012F	3,000	15,000	P	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC016F	3,000	15,000	N	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC020F	3,000	15,000	02	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC025F	3,000	15,000	C	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC035F	3,000	15,000	03	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC050F/13.2	3,000	15,000	M	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC075F	3,000	15,000	L	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC110F	3,000	15,000	K	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC150F	3,000	15,000	15	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
nanoSMDC200F	3,000	15,000	T	1.60 (0.063)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV

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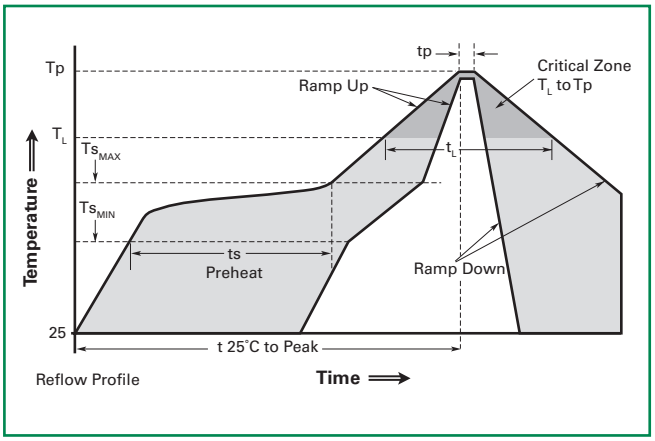
Solder Reflow Recommendations

Profile Feature	Pb-Free Assembly
Average ramp up rate (Ts_{MAX} to Tp)	3°C/s max
Preheat	
• Temperature min (Ts_{MIN})	150°C
• Temperature max (Ts_{MAX})	200°C
• Time (ts_{MIN} to ts_{MAX})	60-120 s
Time maintained above:	
• Temperature (T_L)	217°C
• Time (t_L)	60-150 s
Peak/Classification temperature (Tp)	260°C
Time within 5°C of actual peak temperature	
Time (tp)	30 s max
Ramp down rate	3°C/s max
Time 25°C to peak temperature	8 min max

Note: All temperatures refer to topside of the package, measured on the package body surface.



Solder Reflow

- Recommended reflow method: IR, hot air, nitrogen.
- Recommended maximum paste thickness: 0.25mm (0.010in)
- Devices can be cleaned using standard methods and aqueous solvents.
- Experience has shown the optimum conditions for forming acceptable solder fillets occur when a reasonable amount of solder paste is placed underneath each device's termination. As such, we request that customers comply with our recommended solder pad layouts.
- Customer should validate that the solder paste amount and reflow recommendations meet its application.
- We request that customer board layouts refrain from placing raised features (e.g. vias, nomenclature, traces, etc.) underneath PolySwitch devices. It is possible that raised features could negatively impact solderability performance of our devices.

Rework

- Standard industry practices. (Please also avoid direct contact to the device.)

Part Ordering Number System

nanoSMDC 050 F /13.2 -2

- **-2** — **Packaging**
  2 = Tape and Reel
- **/13.2** — **Alternative Voltage Rating (If Applicable)**
- **F** — **Lead Free**
- **050** — **Hold Current Indicator**
- **nanoSMDC** — **Product Series**

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Tape and Reel Specifications

Description	nanoSMDC EIA 481-1	
	nanoSMDC020F nanoSMDC025F nanoSMDC035F nanoSMDC050F/13.2 nanoSMDC075F nanoSMDC110F nanoSMDC150F	nanoSMDC010F nanoSMDC012F nanoSMDC016F nanoSMDC200F
W	8.0 ± 0.30	8.0 ± 0.30
P_0	4.0 ± 0.10	4.0 ± 0.10
P_1	4.0 ± 0.10	4.0 ± 0.10
P_2	2.0 ± 0.05	2.0 ± 0.05
A_0	1.95 ± 0.10	1.95 ± 0.10
B_0	3.50 ± 0.1/-0.08	3.5 ± 0.10
B_1 max	4.35	4.35
D_0	1.55 ± 0.05	1.55 ± 0.05
F	3.50 ± 0.05	3.50 ± 0.05
E_1	1.75 ± 0.10	1.75 ± 0.10
E_2 min	6.25	6.25
T max	0.3	0.3
T_1 max	0.1	0.1
K_0	0.89 ± 0.1	1.27 ± 0.1
A max	185	185
N min	50	50
W_1	8.4 + 1.5/-.00	8.4 + 1.5/-.00
W_2 max	14.4	14.4

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Tape and Reel Diagrams

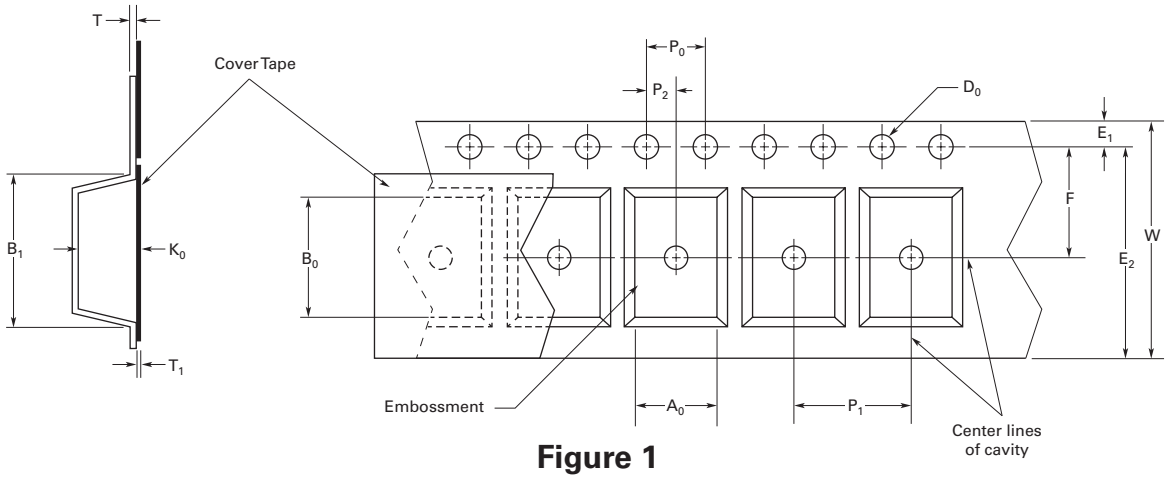

Figure 1

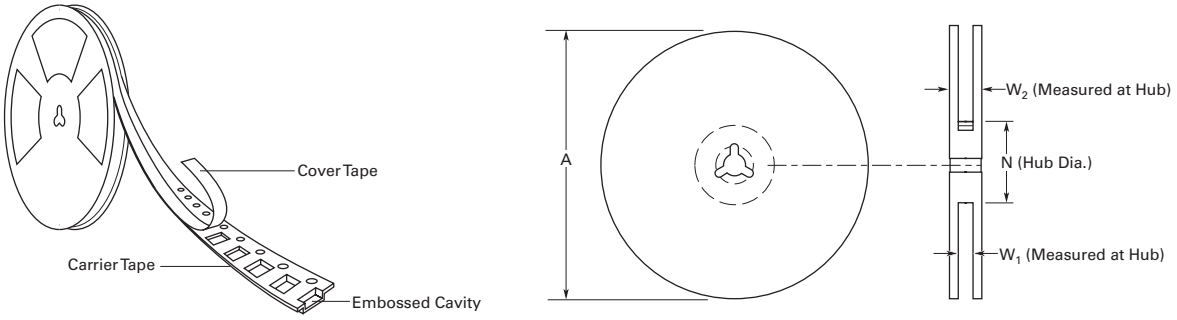

Figure 2

WARNING

- Users should independently evaluate the suitability of and test each product selected for their own application.
- Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- These devices are intended for protection against damage caused by occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Contamination of the PPTC material with certain silicone-based oils or some aggressive solvents can adversely impact the performance of the devices.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- PPTC devices are not recommended for installation in applications where the device is constrained such that its PTC properties are inhibited, for example in rigid potting materials or in rigid housings, which lack adequate clearance to accommodate device expansion.
- Operation in circuits with a large inductance can generate a circuit voltage (Ldi/dt) above the rated voltage of the device.